

Abstract

RESIN COMPOSITION, PREPREG, AND LAMINATE

[Problem to be Solved]

It is an object of the present invention to provide, without using a halogenated compound or a phosphorus compound, a resin composition for printed wiring boards, a prepreg, a laminate, and a metal foil-clad laminate, each of which has high-degree flame retardance, has a low water absorption ratio and a high glass transition temperature, and has a high elastic modulus at high temperature.

[Solution]

A resin composition according to the present invention comprises: a specific maleimide compound (A); a cyanate ester compound (B); a non-halogen epoxy resin (C); and an inorganic filler (D).